L Number	Hits	Search Text	DB	Time stamp
1	758731	(semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 00:35
2	238892	(via opening hole through hole) same ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14
3	241249	(via opening hole through hole plug) same ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 00:37
4	144921	<pre>(via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14 00:39
5	2202	<pre>((via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))) same (taper tapered concave concavity)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/14
6	1067	<pre>(((via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))) same (taper tapered concave concavity)) same (electrode pads terminals contacts)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 00:48
7	671	<pre>((((via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))) same (taper tapered concave concavity)) same (electrode pads terminals contacts)) and((circuit capacitor) (thin adj4 film))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 00:50
8	671	<pre>((((via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))) same (taper tapered concave concavity)) same (electrode pads terminals contacts)) and ((circuit capacitor) (thin adj4 film))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 00:50
9	671	((((via opening hole through hole plug) with ((semiconductor silicon si gaas crystal single crystalline) with (substrate carrier board))) same (taper tapered concave concavity)) same (electrode pads terminals contacts)) and (circuit capacitor (thin adj4 film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 00:51